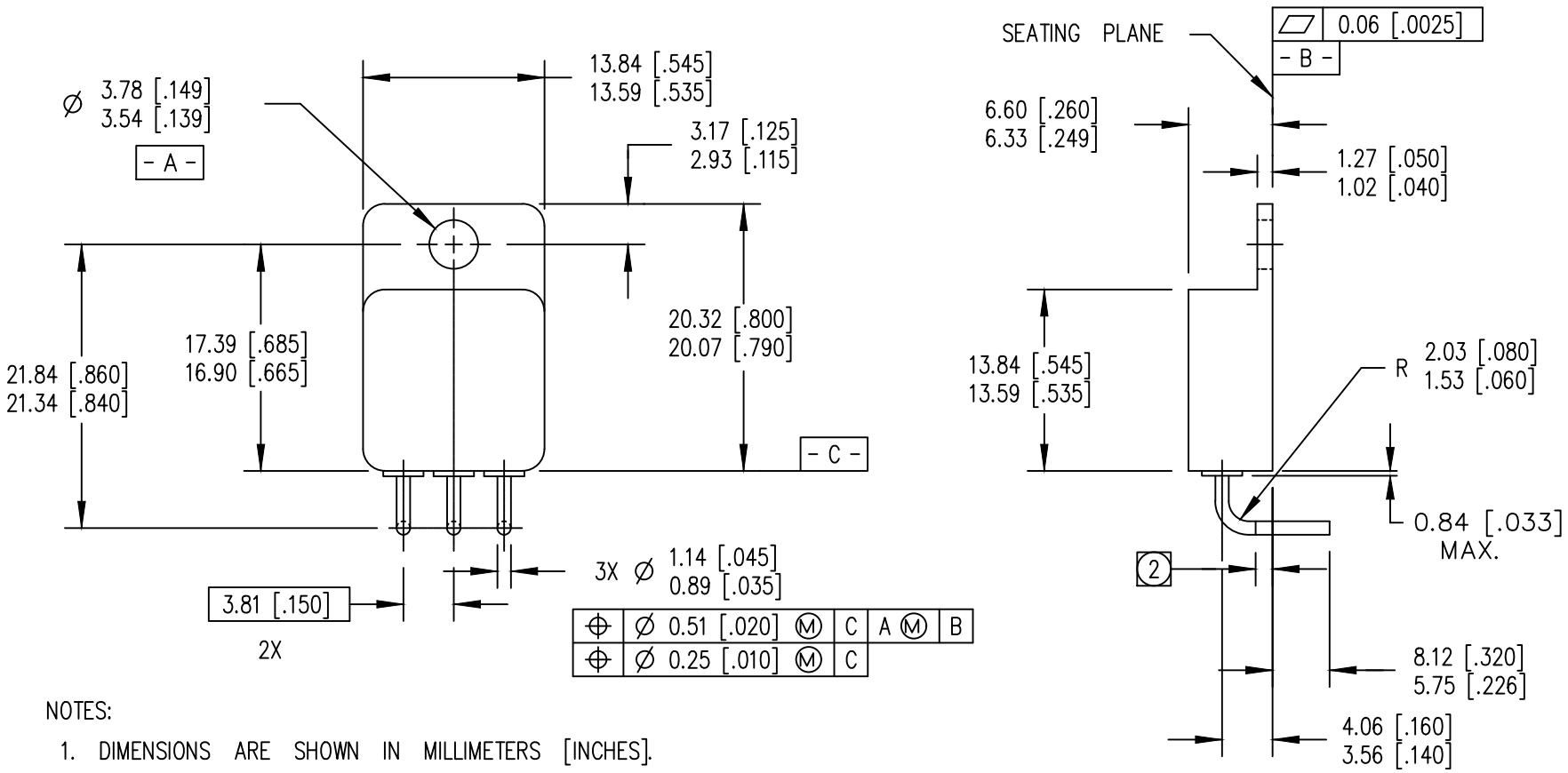
REV.	DESCRIPTION	ECN	DATE
F	INITIAL RELEASE	1120_10056	8–13–24



NOTES:

1. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
2. LEADS ARE SOLDER DIPPED 1.27 [.050] MINIMUM BEYOND THE SEATING PLANE.
3. STANDARD FINAL FINISH ON ALL TERMINALS IS SOLDER ALLOY 63%Sn 37%Pb.

IOR HiRel
An Infineon Technologies Company

TITLE: TO-254AA LEADFORM
90° DOWN, PACKAGE OUTLINE

DRAWING NO. D100709G-WEB

REV F